


# MATERIAL DECLARATION SHEET



Material Number	CDMSP10-0504M			
Product Line	Semiconductor Products			
Compliance Date	2008/7/29			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	1.0000	Silicon	7440-21-3	100.00%	3.571%	3.571%
2	Lead frame	Copper Alloy	7.4636	Copper	7440-50-8	93.295%	26.656%	28.572%
			0.2000	Iron	7439-89-6	2.50%	0.714%	
			0.0080	Phosphorus	7723-14-0	0.10%	0.029%	
			0.0080	Zinc	7440-66-6	0.10%	0.029%	
			0.3200	Silver	7440-22-4	4.00%	1.143%	
			0.0004	Lead	7439-92-1	0.005%	0.001%	
3	Epoxy	Polymer	0.2800	Acrylic resin	Confidential	29.47%	1.0524	3.571%
			0.1500	Polybutadiene derivative	Confidential	15.79%	0.5639	
			0.0300	Butadiene copolymer	Confidential	3.16%	0.1128	
			0.2500	Acrylate	Confidential	26.32%	0.9399	
			0.0500	Epoxy resin	Confidential	5.26%	0.1878	
			0.0500	Additive, not to declare	Confidential	5.26%	0.1878	
			0.0700	Silica	68611-44-9	7.37%	0.2632	
			0.0700	Boron	7440-42-8	7.37%	0.2632	

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4	Cu wire	Noble metal	0.9750	Copper	7440-50-8	97.50%	3.482%	3.571%
			0.0250	Palladium	7440-05-3	2.50%	0.089%	
5	Mold Compound	Polymer	0.4500	Epoxy resin-1	Confidential	3.00%	1.607%	53.572%
			0.4500	Epoxy resin-2	Confidential	3.00%	1.607%	
			0.4500	Epoxy resin-3	Confidential	3.00%	1.607%	
			0.4500	Phenol Resin	Confidential	3.00%	1.607%	
			0.0300	Carbon Black	1333-86-4	0.20%	0.107%	
			12.8700	Amorphous Silica	60676-86-0	85.80%	45.966%	
			0.3000	Crystal Silica	14808-60-7	2.00%	1.071%	
6	Plating	Plating	1.9998	Tin	7440-31-5	99.99%	7.142%	7.143%
			0.0002	Misc, not to declare	/	0.01%	0.001%	
Total weight			<b>27.95 mg</b>					

This Document was updated on: 2015/11/27

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.